- Package Options Include Plastic "Small Outline" Packages, Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

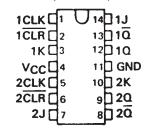
description

The '73, and 'H73, contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '73, and 'H73, are positive pulse-triggered flip-flops. J-K input is loaded into the master while the clock is high and transferred to the slave on the high-to-low transition. For these devices the J and K inputs must be stable while the clock is high.

The 'LS73A contains two independent negative-edge-triggered flip-flops. The J and K inputs must be stable one setup time prior to the high-to-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Ω output low and the $\overline{\Omega}$ output high.

The SN5473, SN54H73, and the SN54LS73A are characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN7473, and the SN74LS73A are characterized for operation from 0 °C to 70 °C.

SN5473, SN54LS73A . . . J OR W PACKAGE SN7473 . . . N PACKAGE SN74LS73A . . . D OR N PACKAGE (TOP VIEW)



73
FUNCTION TABLE

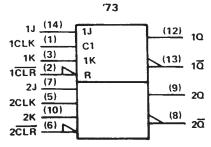
	INPUT	S		OUT	PUTS
CLR	CLK	J	K	Q	ā
L	×	Х	Х	L	Н
Н	Ţ	L	L	00	\bar{a}_0
Н	工	Н	L	Н	L
Н	ъ.	L	Н	L	Н
Н	T	Н	Н	TOG	GLE

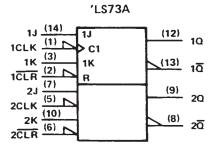
'L\$73A FUNCTION TABLE

	INPUT	rs		OUTP	UTS
CLR	CLK	J	K	Q	₫
L	X	Х	Х	L	н
н	1	L	L	αo	\overline{a}_{0}
н	1	Н	L	Н	L
н	1	L	Н	L	н
н	1	Н	Н	TOG	GLE
н	Н	Х	Х	αo	\bar{a}_0

FOR CHIP CARRIER INFORMATION.
CONTACT THE FACTORY

logic symbols†



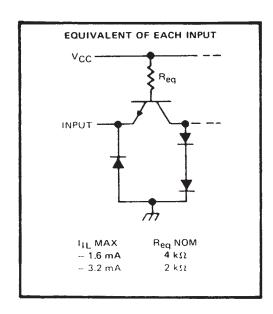


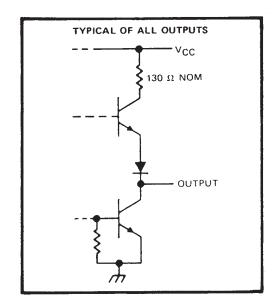
[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

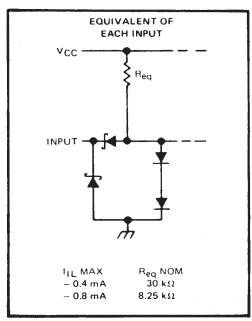
'73

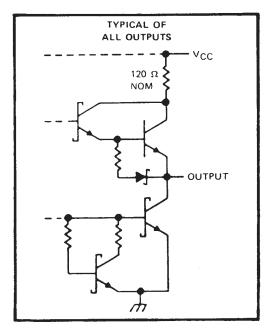
'LS73

schematics of inputs and outputs

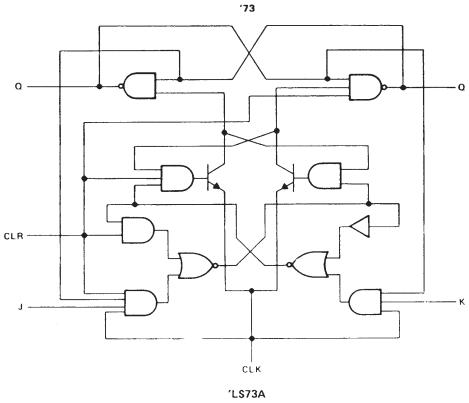


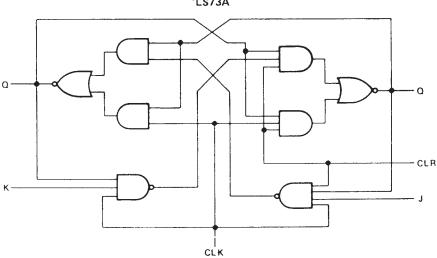






logic diagrams (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (See Note 1)		7 V
Input voltage: '73		5.5 V
′LS73A		7 V
Operating free-air temperature range:	SN54'	-55°C to 125°C
operating that an early are a series of	SN74'	0° C to 70°C

NOTE 1: Voltage values are with respect to network ground terminal.



SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

SDLS118 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

				SN547	3		SN747	3	IMIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage		2			2			>
VIL	Low-level input voltage				8.0			0.8	٧
ЮН	High-level output current				-0.4			- 0.4	mA
loL	Low-level output current				16			16	mA
		CLK high	20			20			
tw	Pulse duration	CLK low	47			47			ns
		CLR low	25			25			
t _{su}	Input setup time before CLK f		0			0			ns
th	Input hold time data after CLK↓		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			EST CONDITION	unt.		SN5473			SN7473		
PA	RAMETER	11	MIN	TYP#	MAX	MIN	TYP‡	MAX	UNIT		
VIK		V _{CC} = MIN,	I _I = - 12 mA				- 1.5			- 1.5	V
Vон		V _{CC} = MIN, I _{OH} = - 0.4 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,	2.4	3.4		2.4	3.4		٧
VOL		V _{CC} = MIN, I _{OL} = 16 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,		0.2	0.4		0.2	0.4	V
11		V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
ЧН	J or K	V _{CC} = MAX,	V ₁ = 2.4 V				40 80			40 80	μА
	J or K						- 1.6			- 1.6	
ItL	CLR	V _{CC} = MAX,	V ₁ = 0.4 V				- 3,2			- 3.2	mA
	CLK		·				- 3.2			- 3.2	}
los§		V _{CC} = MAX			- 20		– 57	- 18		- 57	mA
Icc1		V _{CC} = MAX,	See Note 2			10	20	<u> </u>	10	20	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER#	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				15	20		MHz
^t PLH	CLR	₫ .			16	25	ns
^t PHL	CLA	Q	$R_L = 400 \Omega$, $C_L = 15 pF$	-	25	40	กร
^t PLH	CLK	Q or Q			16	25	ns
^t PHL	CLK	2 07 02			25	40	ns

[#]f_{max} = maximum clock frequency: tp_{LH} = propagation delay time, low-to-high-level output; tp_{HL} = propagation delay time, high-to-low-level output.

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $^{^{\}ddagger}$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 \,^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time.

¹ Average per flip-flop.

recommended operating conditions

			SI	N54LS7	3A	Si	174LS7	3A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage		2			2			٧
VIL	Low-level input voltage				0.7			0.8	V
Іон	High-level output current				- 0.4			- 0.4	mA
lOL	Low-level output current				4			8	mA
fclock	Clock frequency		0		30	0		30	MHz
	Pulse duration	CLK high	20			20			
t _W	ruise duration	CLR low	25			20			กร
	Con an almost had not Ol 161	data high or low	20			20			
t _{su}	Set up time-before CLK4	CLR inactive	20			20			ns
th	Hold time-data after CLK↓		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	RAMETER		ST CONDITION	et	SI	N54LS73	3A	Si	N74LS7:	3A	UNIT
PA	ARAMETER		251 COMPITION	3.	MIN	TYP#	MAX	MIN	TYP#	MAX	UNIT
VIK		V _{CC} = MIN,	$t_1 = -18 \text{ mA}$				- 1.5			- 1.5	V
Voн		V _{CC} = MIN, I _{OH} = - 0.4 mA	V _{IH} = 2 V,	V _{IL} = MAX,	2.5	3.4		2.7	3.4		٧
\/ - ·		V _{CC} = MIN, I _{OL} = 4 mA	V _{IL} = MAX,	V _{IH} = 2 V,		0.25	0.4		0.25	0.4	V
VOL		V _{CC} = MIN, I _{OL} = 8 mA	VIL = MAX,	V _{IH} = 2 V,					0.35	0.5	v
	J or K						0.1			0.1	
l _l	CLR	V _{CC} = MAX,	V ₁ = 7 V				0.3			0.3	mA
	CLK						0.4			0.4	
	J or K	-					20			20	
чн	CLR	V _{CC} = MAX,	V ₁ = 2.7 V				60			60_	μА
	CLK						80			80	
	J or K	V	V = 0.4.V				0.4			- 0,4	mA
11L	CLR or CLK	V _{CC} = MAX,	V = 0.4 V				- 0.8			- 0.8	IIIA
los\$		V _{CC} = MAX,	See Note 4		- 20		– 100	- 20		- 100	mA
ICC (T	otai)	V _{CC} = MAX,	See Note 2			4	6		4	6	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	Mir	i TYP	MAX	UNIT
f _{max}				3	45		MHz
tPLH	CLR or CLK	Q or Q	$R_{\perp} = 2 k\Omega$, $C_{\perp} = 15$	i pF	15	20	ns
tPHL	CER OF CER	Q or Q			15	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_O = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.





24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
5000 0075404004	(1)	ODID		44	-	(2)	(6)	(3)	55.1- 405	(4/5)	
5962-9675101QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9675101QC A	Sample
										SNJ54LS73AJ	
5962-9675101QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9675101QD	Sample
										Α	Sample
										SNJ54LS73AW	
5962-9675101QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9675101QD A	Sample
										SNJ54LS73AW	
SN54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS73AJ	C 1
											Sample
SN54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS73AJ	Sample
SN74LS73AD	ACTIVE	SOIC	D	14	50	Green (RoHS	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	Sample
						& no Sb/Br)					Sample
SN74LS73AD	ACTIVE	SOIC	D	14	50	Green (RoHS	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	Sample
						& no Sb/Br)					
SN74LS73ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	Sample
SN74LS73ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	
3N/4L3/3ADR	ACTIVE	SOIC	D	14	2500	& no Sb/Br)	CO NIPDAO	Level- 1-260C-UNLIM	0 to 70	LS/3A	Sample
SN74LS73ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	C 1
						& no Sb/Br)					Sample
SN74LS73ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	Sample
						& no Sb/Br)					battiple
SN74LS73AN	ACTIVE	PDIP	N	14	25	Green (RoHS	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	Sample
ON 7 41 O 7 O A N	A OTIV / E	DDID		4.4	0.5	& no Sb/Br)	OLLNIDDALL	N / A for Disc. Top.	0.1- 70	ONIZ 41 OZOANI	
SN74LS73AN	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	Sample
SN74LS73ANE4	ACTIVE	PDIP	N	14	25	Green (RoHS	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	
0111 1207 07 1112 1	7.01172	. 5		٠.	20	& no Sb/Br)	001111 2710	1177 Kilom kg Typo	0.10.70	0117 1207 07 111	Sample
SN74LS73ANE4	ACTIVE	PDIP	N	14	25	Green (RoHS	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	Sample
						& no Sb/Br)					Sample
SNJ54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9675101QC	Sample
										A SN 1541 S72A 1	
										SNJ54LS73AJ	



PACKAGE OPTION ADDENDUM

24-Aug-2018

Orderable Device	Status	Package Type			_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9675101QC A SNJ54LS73AJ	Samples
SNJ54LS73AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9675101QD A SNJ54LS73AW	Samples
SNJ54LS73AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9675101QD A SNJ54LS73AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

24-Aug-2018

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS73A, SN74LS73A:

Catalog: SN74LS73A

Military: SN54LS73A

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

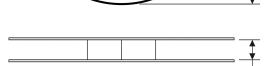
PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS73ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012



*All dimensions are nominal

	Device	Device Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
I	SN74LS73ADR	SOIC	D	14	2500	367.0	367.0	38.0	

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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